

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/15268
1.3 Title of PCN	ASE Kaohsiung (Taiwan) additional source for STM32H56x and STM32H57x listed products in VQFPN 8X8 package
1.4 Product Category	STM32H56x and STM32H57x
1.5 Issue date	2026-04-09

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	KRISZTINA NEMETH
2.1.2 Phone	+49 8946006
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ASE Kaohsiung (Taiwan)

4. Description of change

	Old	New
4.1 Description	Current assembly sites: - JSCC (China) in Copper Palladium wire	Current assembly site : - JSCC (China) in Copper Palladium wire Additional assembly site for extended capacity: - ASE KaoHsiung (Taiwan) in copper palladium wire
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact on Form, Fit, Function	

5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST General Purpose and Automotive Microcontrollers division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	traceability ensured by ST Internal tools
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7. Timing / schedule

7.1 Date of qualification results	2025-10-24
7.2 Intended start of delivery	2025-10-24
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	15268 MDG-GPM-RER2323 ASE UQFN 32L_48L_ VQFN 68LCuPd wires STM32-plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-04-09

9. Attachments (additional documentations)
15268 Public product.pdf 15268 MDG-GPM-RER2323 ASE UQFN 32L_48L_ VQFN 68LCuPd wires STM32-plan.pdf 15268 _Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H562RGV6	
	STM32H562RIV6	
	STM32H563RIV6	
	STM32H573RIV6	
	STM32H563RGV6	

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**PRODUCT/PROCESS
CHANGE NOTIFICATION
PCN15268
– Additional information**

**ASE Kaohsiung (Taiwan) additional source for STM32H56x and
STM32H57x listed products in VQFPN 8X8 package.**

MDRF – General Purpose and Automotive Microcontrollers (GPAM)

What are the changes?

Introduction of an additional assembly line to continue our path through the deployment of our Low-cost wire strategy to secure our supply chain.

Changes described in table below:

	Existing back-end line	Added back-end line
Assembly site	StatsChipPAC JSCC Jiangyin (China)	ASE Kaohsiung (Taiwan)
Leadframe	Copper, Post plated	Copper, Post plated
Lead Finishing	Pure Tin (e3)	Pure Tin (e3)
Molding Compound	G631BQ-CJ	G631H
GLUE	EN4900GC	EN4900G
Wire	Copper Palladium 0.8mil	Copper Palladium 0.8mil
PP code marking	GQ	AA

How can the change be seen?

Package top view Marking will **NOT** display 2D marking – package is too small.

Package top view marking for VFQFPN 8X8 68L with Commercial product **STM32H562RIV6**
example as below



Y WW : Year Week (manufacturing date)

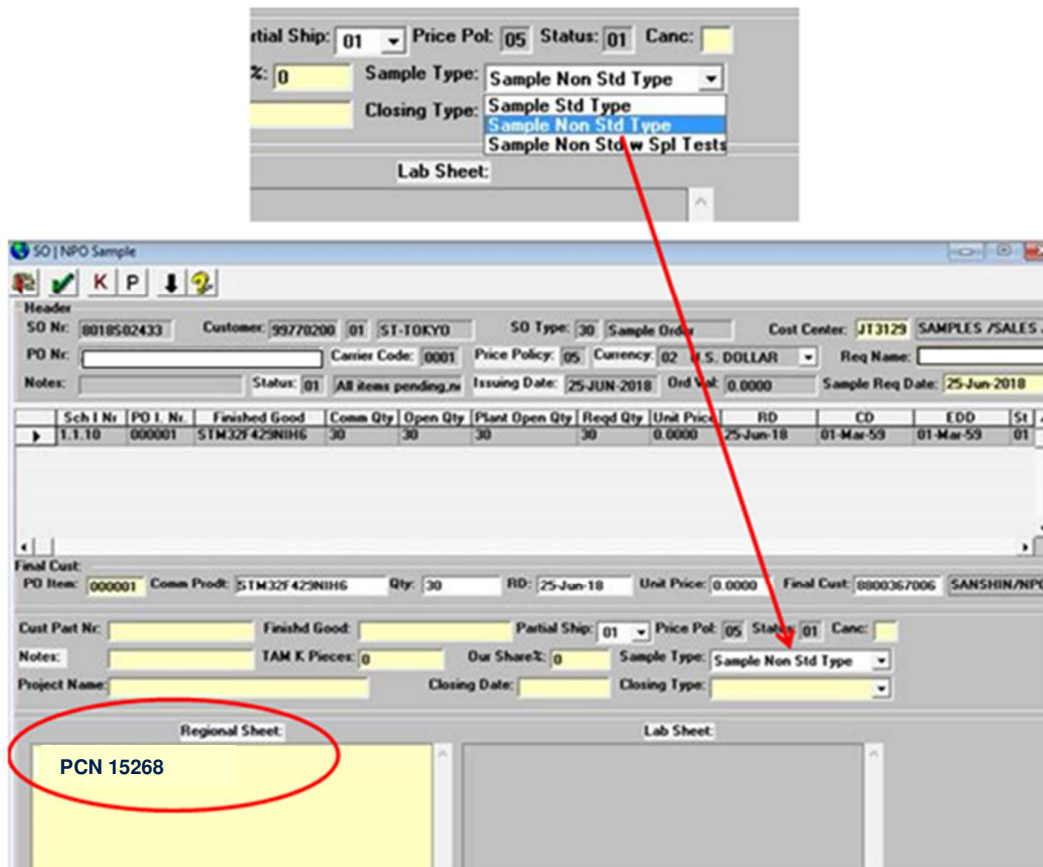
PP : Assembly Plant code

Please refer to Technical Note **TN1433** for package marking details.

How to order samples?

For all samples request linked to this PCN, please:

- place a **Non-standard** sample order (choose Sample Non Std Type from pull down menu).
- insert the PCN number "**PCN15268**" into the NPO Electronic Sheet/**Regional Sheet**.
- request sample(s) through Notice tool, indicating a single Commercial Product for each request.



The screenshot displays the 'NPO Sample' software interface. At the top, a dropdown menu for 'Sample Type' is open, showing options: 'Sample Std Type', 'Sample Non Std Type' (highlighted), and 'Sample Non Std w Spl Tests'. A red arrow points from this menu to the 'Sample Type' field in the 'Regional Sheet' section below. In the 'Regional Sheet' section, the text 'PCN 15268' is circled in red. The interface also shows various fields for 'SO No.', 'Customer', 'Carrier Code', 'Price Policy', 'Currency', 'Issuing Date', 'Ord Val', 'Sample Req Date', 'Comm Qty', 'Open Qty', 'Plant Open Qty', 'Reqd Qty', 'Unit Price', 'RD', 'CD', 'EDD', 'St', 'Cust Part Nr', 'Finishd Good', 'Partial Ship', 'Price Pol', 'Status', 'Canc', 'Notes', 'TAM K Pieces', 'Our Share%', 'Closing Date', and 'Closing Type'.

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STRIVE
FOR EXCELLENCE

MDG-GPM-RER2323-PCN15268 ASEKH UQFN32L_48L & VQFN68L CuPd wire Qualification

Reliability Evaluation Plan

March 4th , 2026

MDRF GPAM Q&R

MDG-GPM-RER2323-PCN15268

ASE UQFN32L_48L & VQFN68L CuPd wire Package Test Vehicles

Package line	Assembly Line	Package	Version	Device (RawLine Code)	Diffusion Process Plant	Number of Reliability Lots	Full
QFN	UQFPN 5x5	32L	BORLV OFF	MG*435	TSMC N90	1	Full
	UQFPN 5x5	32L	Std	MG*466	TSMC N90	1	Full
	UQFPN 7x7	48L	1sp	MI*460	TSMC N90	1	Full
	VQFPN 8x8	68L	Legacy	GB*484	E40 Crolles	1	Full

Reliability strategy:

- ASEKH (Taiwan) QFN assembly line is qualified with 3 full reliability lots with N90 TSMC technology.
- Then E40 Crolles in VQFN68L package will be qualified on same assembly line with 1 reliability lot.

MDG-GPM-RER2323-PCN15268

ASE UQFN32L_48L & VQFN68L CuPd wire

Reliability plan

(*) tests performed after preconditioning

Reliability Trial & Standard		Test Conditions	Pass Criteria	Unit per Lot	Lot qty
PC	Pre Conditioning: Moisture Sensitivity Jedec Level 3 J-STD-020/ JESD22-A113	Bake (125°C / 24 hrs) Soak (30°C / 60% RH / 192 hrs) for level 3 Convection reflow: 3 passes	3 passes MSL3	308	4
Uhast(*)	UnBiased Highly Accelerated Temperature and Humidity Stress JESD22 A118	130°C, 85%RH, 2.3 atm	96h	77	4
TC(*)	Thermal Cycling JESD22 A104	-65°C +150°C	500cy	77	4
THB(*)	Biased temperature & humidity stress JESD22 A101	85°C, 85% RH bias	1000h	77	4
HTSL	High Temperature Storage Life JESD22 A103	150°C- no bias	1000h	77	4
Construction analysis	ST internal specifications	Ball shear, pull test, IMC inspection , internal analysis	NA	50	4
ESD	ESD Charge Device Model JEDEC JS-002	Aligned with device datasheet	Aligned with device datasheet	3	4

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Public Products List

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PCN Title : ASE Kaohsiung (Taiwan) additional source for STM32H56x and STM32H57x listed products in VQFPN 8X8 package

PCN Reference : EMBEDDED PROCESSING/26/15268

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32H562RGV6	STM32H563RIV6	STM32H573RIV6TR
STM32H562RIV6	STM32H563RGV6	STM32H573RIV6

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